



### POWER DISSIPATION (TO-252-5)

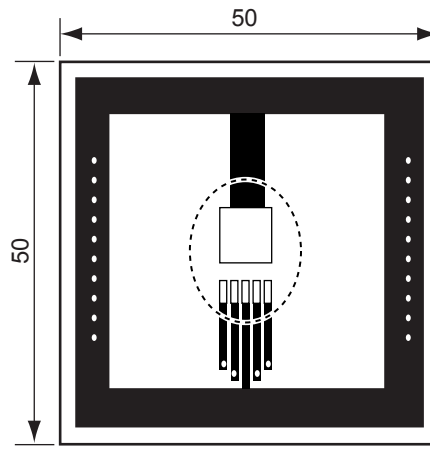
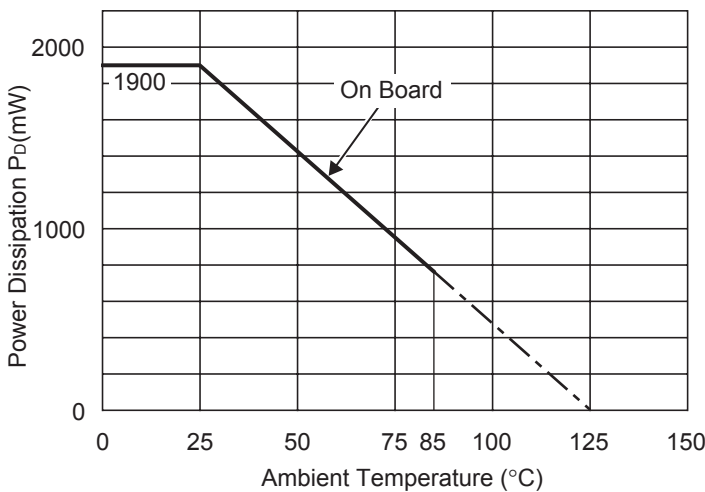
This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	50mm × 50mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 24pcs

Measurement Result (T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

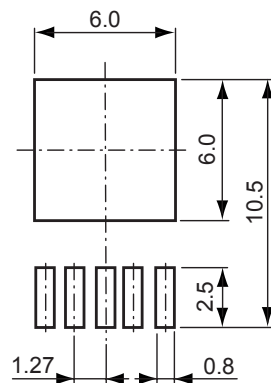
	Standard Land Pattern
Power Dissipation	1900mW
Thermal Resistance	$\theta_{ja}=(125-25^\circ\text{C})/1.9\text{W}=53^\circ\text{C/W}$



Measurement Board Pattern

○ IC Mount Area Unit : mm

### RECOMMENDED LAND PATTERN



(Unit: mm)